## 505155514 10/23/2018

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JIN HO BAEK	09/27/2018

#### **RECEIVING PARTY DATA**

Name:	SK HYNIX INC.	
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State/Country: KOREA, REPUBLIC OF		

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16168653

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	W. WILLIAM PARK	
SIGNATURE:	/W. William Park/	
<b>DATE SIGNED:</b> 10/23/2018		
	This document serves as an Oath/Declaration (37 CFR 1.63).	

**Total Attachments: 1** 

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PATENT 505155514 REEL: 047284 FRAME: 0805

# DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	SEMICONDUCTOR CHIP, PRINTED CIRCUIT BOARD, MULTI-CHIP PACKAGE INCLUDING THE SEMICONDUCTOR CHIP ANDPRINTED CIRCUIT BOARD, AND METHOD OF MANUFACTURING THE MULTI-CHIP PACKAGE		
Declaration	As the below named inventor(s), I hereby declare that:  The declaration is directed to:  The attached application, or  United States application or PCT international application number  PCT/KR####################################		
Assignment	is acknowledge, and other good and assign and transfer unto said assigned 2091, Gyeongchung-daero, Buba and the heirs, successors, assigns and exclusive right to the said in possessions and in any and all fore entire rights, title and interest in a therefore in the United States. I therefore in the United States. I therefore right, title, and interest in and legal representatives, to the full end fully and entirely as the same would not been made.  I agree promptly upon request of legal representatives of the assigned the patent and the invention set forticompensation any power of attacontinuation, divisional or reissue, or I hereby covenant that no assignment be made or entered into which would I further covenant that assignee(s) pertinent facts and documents relating equivalents as may be known and ad litigation related thereto and will progrepresentatives any and all papers, i maintain, issue and enforce said apprendiction.	SK hynix inc.  al-eub, Icheon-si, Gyeonggi-do, Republic of Korea and legal representatives of the assignee(s) the full vention in the United States and in its territorial ign countries any and all improvements thereof, the ind to any and all Patents which may be granted reby authorize and request the Director of the U.S. a said United States Patent to said assignee(s), of the to the same, for his sole use and for the use of his of the term for which said Patent may be granted, as have been held by me had this assignment and sale the assignee(s), its heirs, successors, assigns and e(s) to communicate any facts known to it respecting th therein, and to execute and deliver without further orney, Assignment, application, whether original,	
	Inventor Name (First Middle LAST):	Jin Ho BAEK	
Legal Name Of Inventor	Inventor Signature:	Jin HO BAEK	

☐ A total of \_ supplemental sheet(s) are attached hereto for additional inventors, if any.

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